



Novel Technologies for Metal Microjoining

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Message from the Guest Editors

Microjoining is a critical process in microelectronic packaging, and is crucial for manufacturing many other extremely small components, devices and systems, such as medical implants, sensors and transducers, batteries, and optoelectronics. Generally, microjoining provides mechanical support, electrical connection, and environmental protection for assembly of electronic and biomedical devices. Effective microjoining has become one of the most essential technical prerequisites for success in manufacturing at ever-smaller scales. While many microjoining processes and applications become commonplace, microjoining continues to face fresh challenges because of ever advancing miniaturization. This Special Issue aims to give an updated outlook on the application of novel microjoining technology to metals. We invite you to submit scientific manuscripts that present new findings on materials, structures, and processes in microjoining using experimental analysis, numerical simulation and intelligent algorithms. Novel findings regarding nanojoining and other bottom-up assembly techniques are also welcome, provided that the technology can be used for metals.





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Message from the Editorial Board

Metallic materials play a vital role in the economic life of modern societies; contributions are sought on fresh developments that enhance our understanding of the fundamental aspects related to the relationships between processing, properties and microstructure – disciplines in the metallurgical field ranging from processing, mechanical behavior, phase transitions and microstructural evolution, nanostructures, as well as unique metallic properties – inspire general and scholarly interest among the scientific community.

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